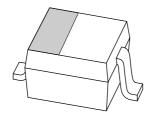
# **DISCRETE SEMICONDUCTORS**

# DATA SHEET



# **1PS76SB10**Schottky barrier diode

Product specification Supersedes data of 1996 Oct 14 2004 Jan 26





Philips Semiconductors Product specification

# Schottky barrier diode

1PS76SB10

# **FEATURES**

- · Low forward voltage
- · Guard ring protected
- Very small plastic SMD package.

# **APPLICATIONS**

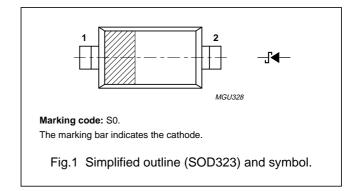
- Ultra high-speed switching
- Voltage clamping
- · Protection circuits
- Blocking diodes.

# **DESCRIPTION**

Planar Schottky barrier diode encapsulated in a SOD323 very small plastic SMD package.

# **PINNING**

PIN	DESCRIPTION	
1	cathode	
2	anode	



# **ORDERING INFORMATION**

TYPE		PACKAGE		
NUMBER	NAME	DESCRIPTION	VERSION	
1PS76SB10	_	plastic surface mounted package; 2 leads	SOD323	

# **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>R</sub>	continuous reverse voltage		_	30	V
I <sub>F</sub>	continuous forward current		_	200	mA
I <sub>FRM</sub>	repetitive peak forward current	$t_p \le 1 \text{ s}; \ \delta \le 0.5$	_	300	mA
I <sub>FSM</sub>	non-repetitive peak forward current	t <sub>p</sub> < 10 ms	_	600	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	125	°C
T <sub>amb</sub>	operating ambient temperature		-65	+125	°C

Philips Semiconductors Product specification

# Schottky barrier diode

1PS76SB10

# **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
V <sub>F</sub>	forward voltage	see Fig.2		
		I <sub>F</sub> = 0.1 mA	240	mV
		I <sub>F</sub> = 1 mA	320	mV
		I <sub>F</sub> = 10 mA	400	mV
		I <sub>F</sub> = 30 mA	500	mV
		I <sub>F</sub> = 100 mA	800	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 25 V; note 1; see Fig.3	2	μΑ
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 1 V; f = 1 MHz; see Fig.4	10	pF

# Note

1. Pulsed test:  $t_p = 300 \ \mu s; \ \delta = 0.02.$ 

# THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	note 1	450	K/W

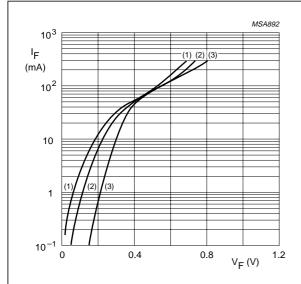
# Note

1. Refer to SOD323 standard mounting conditions.

# Schottky barrier diode

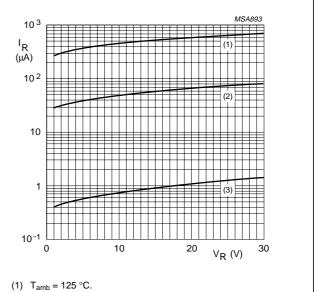
1PS76SB10

# **GRAPHICAL DATA**



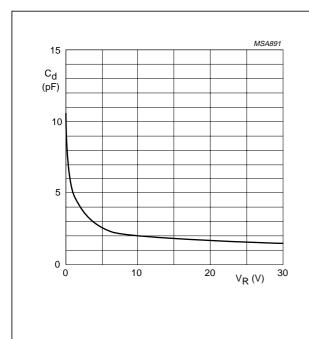
- (1)  $T_{amb} = 125 \, ^{\circ}C$ .
- (2)  $T_{amb} = 85 \,^{\circ}C$ .
- (3)  $T_{amb} = 25 \, ^{\circ}C$ .

Fig.2 Forward current as a function of forward voltage; typical values.



- (2)  $T_{amb} = 85 \, ^{\circ}C$ .
- (3)  $T_{amb} = 25 \, ^{\circ}C$ .

Fig.3 Reverse current as a function of reverse voltage; typical values.



 $T_{amb}$  = 25 °C; f = 1 MHz.

Fig.4 Diode capacitance as a function of reverse voltage; typical values.

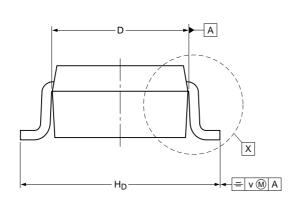
# Schottky barrier diode

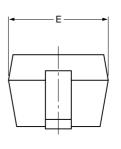
1PS76SB10

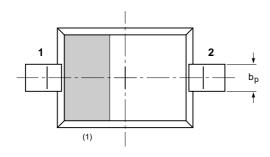
# **PACKAGE OUTLINE**

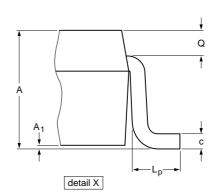
Plastic surface mounted package; 2 leads

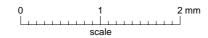
SOD323











# DIMENSIONS (mm are the original dimensions)

mm 1.1 0.05 0.40 0.25 1.8 1.35 2.7 0.45 0.25	UNIT	
	J	
0.8   0.05   0.25   0.10   1.6   1.15   2.3   0.15   0.15	mm	

### Note

1. The marking bar indicates the cathode

OUTLINE	REFERENCES		EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOD323			SC-76			<del>99-09-13</del> 03-12-17

Philips Semiconductors Product specification

# Schottky barrier diode

1PS76SB10

### **DATA SHEET STATUS**

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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For additional information please visit http://www.semiconductors.philips.com. Fax: +31 40 27 24825 For sales offices addresses send e-mail to: sales.addresses@www.semiconductors.philips.com.

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